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Electronic Patent Application Submission
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D. Scott
4/8/03

EFS ID: 24714
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
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Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
Certificate Message Digest: MpGX5uFIKcKaFBVLgmVFTA==
Total Fees Authorized: \$180.0
Payment Category: DA - Deposit Account
Deposit Account Number: 194330
Deposit Account Name: Mark B. Garred



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Electronic Version 1.0.3

Stylesheet Version: 1.0

Submission Type: Information
Disclosure Statement

TRANSMITTAL FORM

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-shi Tae Heon Lee

SUBMITTED BY

Name: Mark B. Garred
Registration Number: 34,823
Electronic Signature Mark: /mbg/ Date Signed: 20030317

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Attached Files:

fee-transmittal
us-information-disclosure-statement

IDSfee.xml
IDSids.xml

Comments:



FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

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Large Entity

TOTAL FEES AUTHORIZED: \$ 180

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ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Submission Of Information Disclosure Stmt Fee		1	1806	\$ 180	\$ 180

Subtotal For Additional Fees: \$ 180



Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-shi Lee

Docket

Number:

AMKOR-052A

Group Art

Unit:

2814

Examiner:

Dilinh P. Nguyen

(6498392 or 6464121 or 6452279 or 6444499 or 6400004 or 6395578 or 6384472 or 6380048 or 6373127 or 6339255 or 6326244 or 6323550 or 6316838 or 6309909 or 6303984 or 6297548 or 6294830 or 6291273 or 6291271 or 6285075 or 6282095 or 6281568 or 6281566 or 6256200 or 6239384 or 6229205 or 6225146 or 6222258 or 6218731 or 6211462 or 6208023 or 6208020 or 6204554 or 6201292 or 6201186 or 6198171 or 6197615 or 6184465 or 6181002 or 6177718 or 6169329 or 6140154 or 6133623 or 6130473 or 6130115 or 6118184 or 6118174 or 6100594 or 6087722 or 6081029).pn.

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03/20/2003 HLE333 00000014 194330 09687048

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US Patent Documents